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Contents

| Title | Authors | Page |
|--|--|------|
| Ceramic Pin Grid Array with Built-in Interconnects to Locate TSV Integrated Ion Trap for Wire Bonding-free Assembly | Peng Zhao, Hong Yu Li, Yu Dian Lim, Wen Wei Seit, Luca Guidoni, Chuan Seng Tan | 1 |
| Optimal design configuration for aluminum pillar fabrication towards fine pitch ultrasonic bonding applications | Imants Cirulis, Silvia Braun, Yevhenii Havryliuk, Oleksandr Selyshchev, Klaus Vogel, Frank Roscher, Maik Wiemer, Harald Kuhn | 6 |
| Comprehensive Stress Analysis of Reflow Based on Embedded Device Package | Donghui Liu, Chuan Chen, Rongwei Gao, Meiyong Su, Fei Ding, Liqiang Cao | 11 |
| Ultra-thick films (>170µm) using single spin coated commercial photoresist: Challenges and solutions | Rui Rocha, Alex Dante, André Cardoso | 16 |
| Simulation and Analysis for Capillarity Underfill Process in High Density FCBGA Packaging | Meiyong Su, Yunting Liu, Yao Yang, Binjie Shi, Qidong Wang, Liqiang Cao | 23 |
| Epoxy based Solder Paste for Flexible Substrate with Laser Assisted Bonding Process | Jang Ki-Seok, Eom Yong-Sung, Choi Gwang-Mun, Kim Kook-Man, Lee Jeong-Soo, Joo Jiho, Jung Kwang-Hoon, Lee Chan-Mi, Oh Jin-Hyuk, Kye In-Seok, Yoo Bong-Sun, Choi Kwang-Seong | 28 |
| 10µm and 5µm Die-to-Wafer direct hybrid bonding | Emilie Bourjot, Alice Bond, Carine Ladner, Nicolas Bresson, Stéphane Moreau, Viorel Balan, Arnaud Cornelis, Renan Bouis, Catherine Euvrard, Noura Nadi, Loic Sanchez, Frank Fournel, Nicolas Raynaud, Pascal Metzger, Eric Olier | 31 |
| Packaging Platform for low to medium Power Packages | Tina Thomas, Thanh Duy Nguyen, Marc Dreissigacker, Martin Blechert, Karl-Friedrich Becker, Tanja Braun, Martin Schneider-Ramelow | 39 |
| Potentials of a SiC Fan-out Wafer Level Package for High Power Application | Piotr Mackowiak, Olaf Wittler, Tanja Braun, Janine Conrad, Michael Schiffer, Martin Schneider-Ramelow | 45 |
| Highly miniaturized modular IoT-Firewall realized by Printed Circuit Board Embedding Technology | David Schütze, Thomas Löher, Sven Schmidt, Christopher Kubischke, Gerhard Schink, Andreas Ostmann, Martin Schneider-Ramelow, Jürgen Thomaß | 49 |
| A Study on Fine-Pitch Convertors for hybrid X-ray Detectors - Using Interposers as Alternative to TSV Technology | Andreas Schneider, Dan Beckett, Navid Ghorbanian, Simon Cross, Matthew Veale, Matthew Wilson, Matthew Hart, John Lipp | 55 |
| Development and characterization of a | Christian Lenz, Steffen Ziesche, Kathrin Reinhardt, Stefan Körner, Andreas | 62 |

| | | |
|---|---|-----|
| monolithic ceramic pre-package for SiC-semiconductor devices based on LTCC technology | Schleetz, Linh Bach, Benjamin Bayer, Ingo Schmidt, Bianca Böttge | |
| Thermal Debonding: A Fundamental to Fan-out Manufacturing | Debbie-Claire Sanchez, Bhaumi Panchal, Sophia Oldeide | 67 |
| Implementation of a prototype IoT-based system for monitoring the health, behavior and stress of cows | Boris Evstatiev, Nikolay Valov, Seher Kadirova, Teodor Nenov | 77 |
| Layout-based tuning solution for reconfigurable SIW resonant sensors | Valentin Buiculescu, Angela Baracu, Cristina Buiculescu | 82 |
| Investigations on experimental data obtained by Electrochemical Impedance Spectroscopy on Supercapacitors Structures | Rodica Negroiu, Paul Svasta, Irina Madalina Ioneci (Burcea), Mihaela Ramona Buga, Cosmin Ungureanu | 87 |
| Manufacturing of Ceramic Based Mechatronic Integrated Devices Using Laser-Direct-Structuring | Philipp Braeuer, Thomas Stoll, Martin Muckelbauer, Alexander Hensel, Joerg Franke, Felix Häußler | 91 |
| Platform for Research on the Conditions of Use of LiFePO₄ Batteries in Order to Increase Their Service Life | Alexandru Vasile, Lucian Perișoară, Irina Bristena Bacîș | 97 |
| Development of a Ultra-Thin Glass Based Pressure Sensor for High-Temperature Application | Karsten Meier, Karlheinz Bock, Christian Endisch, Robin Schulze, Ludwig Reichel, Philip Knoch, Maria Esche | 101 |
| Electrochemical deposition of polyaniline for supercapacitor applications | Marin Gheorghe, Mircea Modreanu, Cornel Cobianu, Simona Gheorghe, Paul Svasta | 106 |
| Electronic System for the Management of a Beehive | George Florea, Norocel Codreanu | 110 |
| Neural Estimator of Sound Speed in Air for Ultrasonic Sensing in Manufacturing Environments | Viorel Nicolau, Mihaela Andrei, George Petrea | 114 |
| Novel Cu-nanowire-based technology enabling fine pitch interconnects for 2.5D/3D Integration | Adil Shehzad, Ran Yin, Panchenko Iuliana, Maik Müller, Steffen Bickel, Jürgen M. Wolf, Olav Birlem, Sebastian Quednau | 118 |
| Selective Deposition of Conductive Particles for Anisotropic Conductive Adhesive Interconnects | Van Long Huynh, Knut Eilif Aasmundtveit, Hoang-Vu Nguyen | 124 |
| Fabrication of a Low Profile Planar Transformer Using Molded Interconnect Device Technology | Tim Nils Bierwirth, Eike Christian Fischer, Folke Dencker, Marc Christopher Wurz | 129 |
| Experimental investigation of multidimensional ultrasonic heavy wire bonding | Claus Scheidemann, Olaf Kirsch, Tobias Hemsel, Walter Sextro | 134 |

| | | |
|---|---|-----|
| Investigations on the Robustness of a Solderless Assembled Electronic Module | Bogdan Mihailescu, Ciprian Ionescu, Daniel Comeaga, Gaudentiu Varzaru, Mihai Branzei | 141 |
| A novel hermetic encapsulation approach for the protection of electronics in harsh environments | Malte Spanier, Jakub Pawlikowski, Martin Ihle, Miguel Dufner, Adrian Goldberg, Norbert Kordas, Steffen Ziesche, Martin Jägge, Holger Kappert, Martin Schneider-Ramelow, Andreas Ostmann | 145 |
| A 3D packaging approach for minimally invasive medical application catheter | Daniel Lieske, Gerd Kropke | 150 |
| Openair-Plasma in Electronics Manufacturing | Nico Coenen | 158 |
| Fluxfree solder paste and process for standard SMD components | Nihesh Mohan, Stefan Langer, Gordon Elger | 163 |
| Low Height Wire bond Looping Technology using Wedge Bonding for the MMIC Package | Ah-Young Park, Jae Hak Lee, Seungman Kim, Sumin Kang, Seongheum Han, Seong-II Kim, Jun-Yeob Song | 169 |
| Digital twin as a tool for evaluating and optimizing flow behavior in encapsulating processes | Lisa Stencil, Joerg Strogies, Bernd Mueller, Ruediger Knofe, Carsten Borwieck, Matthias Heimann | 175 |
| A Tunable High Linearity V-I Converter with FG-MOS Translinear Networks for Low Supply Voltage Applications | Elena Doicaru | 184 |
| Using the car in motion relative wind power for charging the car batteries | Cristian Helera | 190 |
| Printed Circuit Board Orthotropic Material Calibration for Static and Dynamic Loading | Iulia Tinca, Iulian-Ionut Ailinei, Arjana Davidescu | 194 |
| Improving the production quality and robustness of a SO16 sensor package by a simulation based digital twin approach | Heiner Möller, Rainer Dudek, Sven Rzepka, Heiko Knoll, Pascal Hille | 203 |
| PSpice Model for a Graphene Hall Sensor | Ana Cristina Davidaş, Ovidiu Aurel Pop, Alin Grama, Traian Jr. Petrişor | 210 |
| Self-configurable decade box: Design and measurements | Leon Brai, Mihai Bolchis , Ovidiu Blidar | 215 |
| Silicon Process Design Kits Management for Multiple Process | Yves Aubry, Florent Jehannin, Matthieu Remond | 219 |
| Real-Life Functional Tests of Conductive Joints of SMD Components on E Textiles | Martin Hirman, Karel Hamernik, David Kalas, Jiri Navratil, Daniela Moravcova, Frantisek Steiner | 223 |
| Behaviour of printed resistors compatible with | Jiri Hlina, Jan Reboun, Ales Hamacek | 228 |

| | | |
|--|--|-----|
| thick film copper technology | | |
| Using Grubler's Criterion theory to position the electronic components in thermoformed electronics | Frederick Bossuyt, Behnam Madadnia, Jan Vanfleteren | 233 |
| Microfabrication of biocompatible cuff electrodes for upper limb neuroprosthesis | Jairo Ramírez-Sarabia, Saad Rabbani, Lars-Cyrl Blystad, Kristin Imenes | 250 |
| High Resolution Printing of Redistribution Layers for Fan-Out Wafer-Level Packaging by using Ultra-Precise Micro-deposition Technology | Ali Roshanghias, Marc Dreissigacker, Iwona Grądzka-Kurzaj, Łukasz Witczak, Martin Schneider Ramelow, Alfred Binder | 254 |
| Wearable wristband for Bio-signal Monitoring | Kimmo Keränen, Ari Alastalo, Timo Kurkela, Juhani Kemppainen, Esa Tuulari, Jukka Happonen, Rafael Michalczuk | 259 |
| A Modified Exponential Equivalent Parallel Resistance (EPR) Model for Estimating Printed Flexible Supercapacitors Self-Discharge Behavior | Hamed Pourkheirollah, Jari Keskinen, Donald Lupo, Matti Mäntysalo | 264 |
| Feasibility Study of Magnetically Enhanced Interconnects for Integration of Flexible and Stretchable Electronics | Daniel Ernst, Krzysztof Nieweglowski, Karlheinz Bock | 269 |
| Printing of Micrometer-Size Features on Complex Substrates for System Integration | Aneta Wiatrowska, Karolina Fiarczyk, Piotr Kowalczewski, Mateusz Łysień, Łukasz Witczak, Jolanta Gadzalińska, Iwona Grądzka-Kurzaj, Ludovic Schneider, Łukasz Kosior, Filip Granek | 273 |
| Bonding strength in flexible electronics | Tuomas Happonen, Arttu Korhonen, Kari Rönkä | 277 |
| Virtual Collaboration with Agile Methods in Engineering Education 4.0 - Jump in the New Normal with Digital Innovation Units | Monica Ciolacu, Paul Svasta, Bogdan Mihailescu, Alina Elena Marcu, Christina Hansen, Tamara Rachbauer | 282 |
| Status Report of Training Development in the METIS Project Focusing on the WP3.1 Activity | Bálint Medgyes, Balázs Illés, Olivér Krammer, Attila Géczy, Slavka Tzanova, Maria Afsar | 292 |
| Bringing Nanotechnology Closer to Electrical Engineers: Training Course Development for Upskilling in the METIS Project | Bonyár Attila, Zangana Shereen, Tzanova Slavka , Afsar Maria | 297 |
| TIE-M - Promoting Learning with Competition | Philip Coanda, Madalin Moise, Paul Svasta, Daniel Comeaga, Cosmin Moisa | 301 |
| Implementation of a measurement platform for examining passive components and circuits | Otoiu Marian, Svasta Paul, Moise Madalin Vasile | 306 |
| Joint International Master in Smart Systems Integrated Solutions | Knut E Aasmundtveit, Changhai Wang, Marta Rencz, Mervi Paulasto-Kröckel, Kristin Imenes, Marc Desmulliez, Ferenc | 310 |

| | | |
|---|---|-----|
| | Ender, Vesa Vuorinen | |
| Thermal conductivity characterization of an in-house formulated thermal insulating xerogel - epoxy composite adhesive for electronics applications | Serguei Stoukatch, J.-F. Fagnard, G. Roy, P. Laurent, F. Dupont, P.J. Jacques, J.-M. Redouté | 315 |
| Characterization of material adhesion in redistribution multilayer for embedded high-frequency packages | Ran Yin, Krzysztof Nieweglowski, Karsten Meier, Karlheinz Bock | 321 |
| Sintered Silver-Tin Alloy Paste for Die Attach Applications of High Power Electronics Packaging | Wei-Chen Huang, Chin-Hao Tsai, C. R. Kao | 326 |
| Corrosion Study on Cu/SnAg solid-liquid interdiffusion microbumps by salt spray testing with 5 wt.% NaCl solution | Laura Wenzel, Maik Mueller, Iuliana Panchenko, Wolfram Steller, M. Juergen Wolf | 330 |
| In-situ infrared spectroscopy for chemical analysis in electronic packaging processes | Corinna Niegisch, Sabine Haag, Tanja Braun, Ole Hölck, Martin Schneider-Ramelow | 336 |
| Metallurgical aspects and joint properties of Cu-Ni-In-Cu fine-pitch interconnects for 3D integration | Steffen Bickel, Iuliana Panchenko, M. Juergen Wolf | 343 |
| A Comparative Analysis of two Dielectric extraction Methods of a PCB Material for D-Band Applications | Abhijeet Kanitkar, Julia-Marie Köszegi, Ivan Ndip, Oliver Schwanitz | 350 |
| Chemical Mechanical Polishing of Superconducting Metals for Quantum Device Interconnections | Rayane Bani, Romain Crochemore, Florianne Baudin, Cassandre Beluffi, Sebastien Dominguez, Guillaume Rodriguez, Richard Souil, Frédéric Gustavo, Jean Charbonnier, Edouard Deschaseaux, Candice Thomas | 354 |
| Utilizing Co as a contact metallization for wafer-level Cu-Sn-In SLID bonding used in MEMS and MOEMS packaging | Fahimeh Emadi, Vesa Vuorinen, Mervi Paulasto-Kröckel | 359 |
| Printable Reactive Materials for Bonding and Joining | Lukas Stepien, Nazik Aslan, Magdalena Tyszler, Elena Lopez, Elisabeth Zeeh, Romane Palluet, Frank Brückner, Christoph Leyens, Milena Lux | 364 |
| Low temperature sapphire to silicon flip chip interconnects by copper nanoparticle sintering | Xinrui Ji, Joost Romijn, Hendrik Joost Van Ginkel, Xu Liu, Henk Van Zeijl, Guoqi Zhang | 368 |
| Au-(In-Bi) and Ag-(In-Bi) Metallic Bonding for Temperature Sensitive Materials | Hoang-Vu Nguyen, Stéphane Kuziora, Knut Aasmundtveit | 373 |
| Effect of line structures on the self-propagating | Konrad Jaekel, Heike Bartsch, Yesenia | 379 |

| | | |
|--|---|-----|
| reaction of Al/Ni multilayer | Haydee Sauni Camposano, Jens Müller | |
| Effect of low Bi content on mechanical properties of Sn-Bi-Zn-In alloy and its joint with Cu | Hiroshi Nishikawa, Yuli Hirata, Chih-han Yang, Shih-kang Lin | 383 |
| Wafer-scale in-plane micro-optical interconnects for fiber arrays | Roger Kraehenbuehl | 387 |
| Impact of Through Glass Vias Filling on the performance of passive thermal cooling in Photonic Packages | Parnika Gupta, Peter O'Brien, Padraic Morrissey, Kevin Kröhnert, Markus Wöhrmann, Michael Schiffer, Norbert Ambrosius, Christian Kelb | 391 |
| Out-of-plane mirrors for single-mode polymeric RDL using direct laser writing | Akash Mistry, David Weyers, Krzysztof Nieweglowski, Karlheinz Bock | 398 |
| Advances in UV-lithographic patterning of multi-layer waveguide stack for single mode polymeric RDL | David Weyers, Krzysztof Nieweglowski, Karlheinz Bock | 405 |
| Vacuum Packaging of MEMS-based Infrared Detectors | Avishek Roy, Hoang-Vu Nguyen, Hexin Xia, Phillip Papatzacos, Per Øhlckers, Knut E. Aasmundtveit | 410 |
| New opto-packaging concepts with electrical feedthrough and optic-micro-assembly by using laser direct soldering | Dr. -Ing. Wolfgang Reinert, Dr. -Ing. Vanessa Stenchly | 416 |
| Novel fast swept source for real-time optical coherent tomography | Maria Chiara Ubaldi, Eugenio Iannone, Silvia Cassina | 421 |
| Compact Power Electronics System Fabrication by Sintering and Lamination of Components into Build-up Layers of the Printed Circuit Boards | Thomas Löher, Oleg Zeiter, Sven Schmidt, Beatrice Schild, Eckart Hoene, Andreas Ostmann, Martin Schneider-Ramelow | 425 |
| Cu-Sintering on Organic and Inorganic Substrates for Power Modules | Dirk Buße, Jürgen Albrecht, Alexander Dahlbüding, Aaron Hutzler, Malte Spanier, Olaf Rämmer | 430 |
| Defect detection of solder connection layer in power electronic components by laser speckle photometry | Lili Chen, Ulana Cikalova, Beatrice Bendjus | 433 |
| Impact of Aluminum Metallization Reconstruction on the Current Distribution in Power Semiconductors | Marcel Sippel, Simon Hassel, Ralf Schmidt, Mario Sprenger, Christoph Hecht, Jörg Franke | 439 |
| Investigation of inorganic encapsulated power modules with enhanced cooling possibilities | Stefan Behrendt | 446 |
| Implementation of a high voltage power supply for underground cable test | Moise Madalin Vasile , Nedelcu Bogdan Sebastian | 452 |
| Study and power cycling of direct-bonded silver joints as high temperature die-attach for power | Felix Haeussler, Marcel Sippel, Mario Sprenger, Alexander Hensel, Jörg Franke | 456 |

| | | |
|--|---|-----|
| electronics | | |
| Thermal and Thermomechanical Investigations of Power Semiconductor Pre-Packages | Niko Pavliček, Chunlei Liu | 462 |
| Characterization of wetting behavior of commercial flux systems by Impedance measurement techniques | Quang-Duc Pham, Norbert Holle, Jürgen Wilde | 466 |
| Deformation measurement on cross sections of Fan-Out Wafer Level Package by Digital Image Correlation (DIC) | Ingrid Maus, Walter Hartner, Martin Niessner, Bettina Baeumer, Paola Altieri-Weimar | 473 |
| Reliability and Lifetime Estimation of Sintered Silver Die Attach for Different Accelerated Testing Conditions | Freerik Forndran, Jens Heilmann, Martin Metzler, Markus Leicht, Bernhard Wunderle | 480 |
| Electrochemical migration investigation on SAC alloys incorporated by TiO₂ nanoparticles in NaCl solution | Ali Gharaibeh, Bálint MEDGYES | 484 |
| MLCC Acoustic Noise Mitigation via Appropriate Design | Covaci Corina , Florin Burza, Krausz Tamas | 488 |
| State of Health Determination of Batteries by Analyzing the Rate of Increase of Their Temperature | Nadezhda Kafadarova, Sotir Sotirov, Anna Stoyanova, Silviya Stoyanova-Petrova, Diana Stoyanova, Iliya Petrov | 492 |
| Practical Considerations for Using Telcordia SR-332 Reliability Standard Prediction Applied to a DC-DC PoL Converter Case | Dan Butnicu, Radu Tristu | 498 |
| Test Equipment Development and Failure Diagnosis Using Sensor Emulators Built with CMOS Analog Multiplexers | Nicolae Ioan Gross, Paul Svasta | 504 |
| Infrared Measurements of Temperature Anomalies in Electronic Devices | Anna Stoyanova, Borislav Bonev, Nadezhda Kafadarova, Stefan Rizanov | 509 |
| Reliability Improvement of Large BGA-Packages Using Sidefill-Support | Manuel Heine, Karsten Meier, Laura Wenzel, Christian Goetze, Karlheinz Bock | 516 |
| SAC305 solder fatigue crack propagation under 3-point bending cycle test condition | Maofen Zhang, Jens Heilmann , Yuen Sing Chan , Martin Richard Niessner, Paola Altieri-Weimar, Bernhard Wunderle | 522 |
| Thermal behavior of FR4 and Flexible substrates for high output IR LEDs application | Aurelian Botau, Catalin Negrea | 528 |
| Technological Platform for Adjustment and Testing of Hybrid Electronic Voltage Regulators for Cars | Alexandru Vasile, Irina Bristena Bacîș, Lucian Perișoară | 541 |

| | | |
|--|---|-----|
| Low cycle fatigue of thin aluminium and copper layers and their susceptibility to corrosion | Sebastian Breitenreiner, Nadine Pflügler, Reinhard Pufall, Bernhard Wunderle | 545 |
| Crack growth in SAC+ Solders under Low and High Stress Conditions | Maximilian Schmid, Gordon Elger, Joseph Hermann, E Liu, Krishna Bhogaraju | 553 |
| Finite Element Analysis of LED Solder Joints during Power Thermal Cycling | Khalil Maarouf, Christine Roucoules, Helmut Klocker | 560 |
| Predicting thermal resistance of solder joints based on Scanning Acoustic Microscopy using Artificial Neural Networks | Andreas Zippelius, Strobel Tobias, Maximilian Schmid, Hermann Joseph, Gordon Elger, Alwin Hoffmann | 566 |
| Additional use cases for RFID tags by implementing 3D-printed push button functionalities | Pauli Valo, Joonas Kortelainen, Tommi Lehtinen, Johanna Virkki, Sari Merilampi, Mirka Leino | 576 |
| A Novel Dielectric Slot Stripline Structure for Millimeter Wave Flexible Printed Circuit | Lai He, Zhiwei Xu, Lujia Wu, Weiguo He, Chunyi Song | 581 |
| Wearable triple band WLAN antenna on leather belt | Mircea Călin , Paul Svasta | 585 |
| D-band Slotted Substrate Integrated Waveguide (SIW) Bandpass Filter based on Mold Substrate. | Mykola Chernobryvko, Oliver Schwanitz, Murugesan Kavin Senthil, Ivan Ndip, Tanja Braun, Friedrich Müller, Martin Schneider-Ramelow, Abhijeet Kanitkar | 589 |
| Design, Fabrication and Measurement of FOWLP-based Series-Fed Antennas for 6G D-Band MIMO Applications | Thi Huyen Le, Oliver Schwanitz, Ivan Ndip, Friedrich Mueller, Michael P. Kaiser, Tanja Braun, Martin-Schneider Ramelow | 593 |
| Real-time isotropic measurement system based on Software Defined Radio | Annamaria Sârbu, Emil Şorecău, Mirela Şorecău, Simona Miclăuş, Paul Bechet | 597 |
| A Technology Platform for miniaturized 5G-module fabrication by embedding of RF-chips into printed circuit boards | Stefan Kosmider, Thomas Löher, Kavin Murugesan, Uwe Maaß, Andreas Ostmann, Martin Schneider-Ramelow | 603 |
| Wafer-Level Thin Film Encapsulation for RF MEMS Using SiN/SU-8 Membrane | Kanaka Joy, Anurag Swarnkar, Giridhar MS, Amitava DasGupta, Deleep R Nair | 610 |
| Analysis of the Degree of Congestion of WiFi, Bluetooth and ZigBee Communication Media | Loredana-Maria Burciu, Radu-Petru Fotescu, Rodica Constantinescu, Paul Svasta, Madalin Moise | 614 |